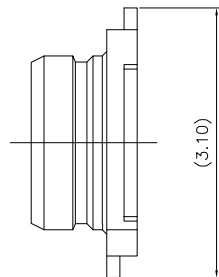
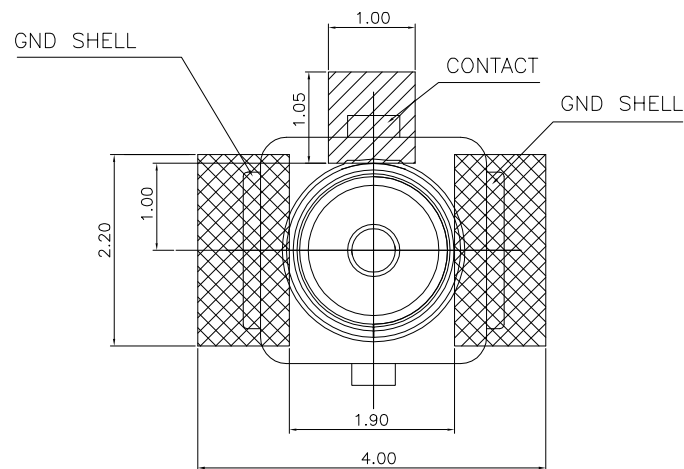


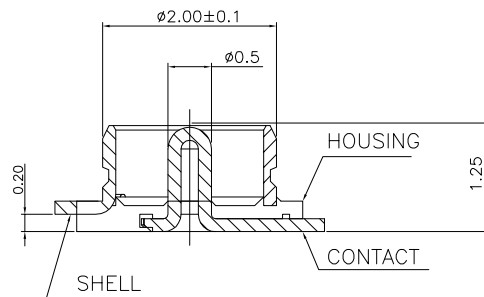
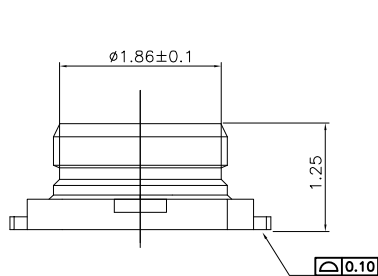
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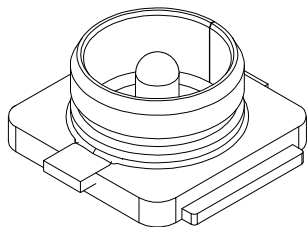
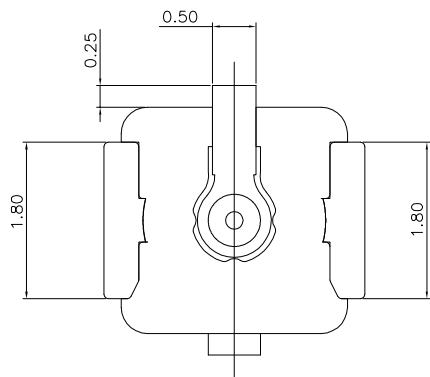
RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.05)



RECOMMENDED PCB LAYOUT
(TOLFRANCF:+0.05)



1. HOUSING MATERIAL: THERMOPLASTIC, WHITE, UL 94V-0;
CONTACT MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA 1u" Min & SOLDER AREA 1u" Min;
SHELL MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA 1u Min & SOLDER AREA 1u Min;
2. PERFORMANCE:
 - 2.1. CONTACT RESISTANCE: 20mOHM Max.
 - 2.2. DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1MINUTE;
 - 2.3. INSULATION RESISTANCE: 500MOHM Min.
3. COPLANARITY: 0.1mm Max.
4. APPLIED TO IR SOLDERING PROCESS.



EXTEND USE			TITLE RF1 BOARD CONN ASSEMBLY DWG				
RF1 BOARD CONN							
GENERAL TOLERANCE 		MATERIAL	APPD		DWG NO 19.002A0		
DIMENTION	ANGLES	QTY	CHD		P/N:		
0. ±0.10	0. ±3.0°						
.0 ±0.05	.0 ±2.0°	FINISHED	DRN		SHEET 1/1		
.00 ±0.03	.00 ±1.0°						
.000 ±0.02							